

MJ N-Channel Enhancement Mode Power MOSFET

Description

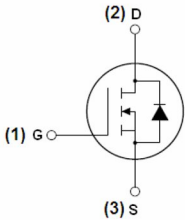
The MJ4090G uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

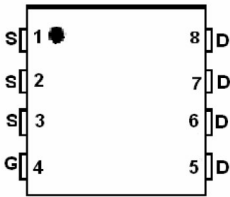
- ◆ $V_{DS}=40V, I_D=90A$
 $R_{DS(ON)}<4m\Omega$ @ $V_{GS}=10V$
 $R_{DS(ON)}<7m\Omega$ @ $V_{GS}=4.5V$
- ◆ High density cell design for ultra low R_{dson}
- ◆ Fully characterized avalanche voltage and current
- ◆ Good stability and uniformity with high E_{AS}
- ◆ Excellent package for good heat dissipation
- ◆ Special process technology for high ESD capability

Application

- ◆ Load switching
- ◆ Hard switched and high frequency circuits
- ◆ Uninterruptible power supply



Schematic diagram



Marking and pin assignment



DFN5X6-8L top view

Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|----------------|---------|----------------|-----------|------------|----------|
| MJ4090G | MJ4090G | DFN5X6-8L | - | - | - |

Absolute Maximum Ratings (Tc =25 °Cunless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|--|-----------------------|------------|------|
| Drain-Source Voltage | V_{DS} | 40 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current-Continuous | I_D | 90 | A |
| Drain Current-Continuous($T_C =100^{\circ}C$) | $I_{D(100^{\circ}C)}$ | 63.5 | A |
| Pulsed Drain Current | I_{DM} | 330 | A |
| Maximum Power Dissipation | P_D | 65 | W |
| Derating factor | | 0.43 | W/°C |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 To 175 | °C |

Thermal Characteristic

| | | | |
|---|-----------------|-----|------|
| Thermal Resistance,Junction-to-Case ^(Note 2) | $R_{\theta JC}$ | 2.3 | °C/W |
|---|-----------------|-----|------|

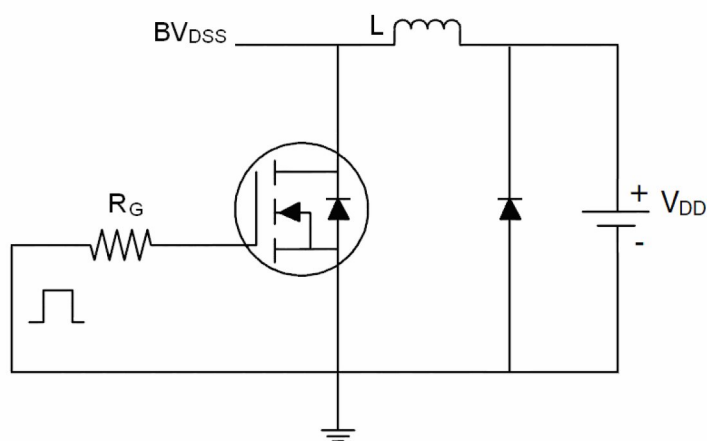
Electrical Characteristics (Tc =25℃unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|---|---------------------|--|------|------|------|------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =250μA | 40 | 45 | - | V |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =40V,V _{GS} =0V | - | - | 1 | μA |
| Gate-Body Leakage Current | I _{GSS} | V _{DS} =±20V,V _{GS} =0V | - | - | ±100 | nA |
| On Characteristics ^(Note 3) | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} ,I _D =250μA | 1.2 | 1.9 | 2.5 | V |
| Drain-Source On-State Resistance | R _{DS(ON)} | V _{GS} =10V, I _D =20A | - | 3.2 | 4.0 | mΩ |
| | | V _{GS} =4.5V, I _D =10A | - | 5.5 | 7.0 | mΩ |
| Forward Transconductance | g _{FS} | V _{DS} =10V,I _D =20A | 26 | - | - | S |
| Dynamic Characteristics ^(Note 4) | | | | | | |
| Input Capacitance | C _{iss} | V _{DS} =20V,V _{GS} =0V, F=1.0MHz | 4600 | 5000 | 5400 | PF |
| Output Capacitance | C _{oss} | | 826 | 898 | 970 | PF |
| Reverse Transfer Capacitance | C _{rss} | | 324 | 351 | 380 | PF |
| Switching Characteristics ^(Note 4) | | | | | | |
| Turn-on Delay Time | t _{d(on)} | V _{DD} =20V,I _D =20A,R _L =1Ω V _{GS} =10V,R _G =3Ω | - | 15 | - | nS |
| Turn-on Rise Time | t _r | | - | 18 | - | nS |
| Turn-Off Delay Time | t _{d(off)} | | - | 52 | - | nS |
| Turn-Off Fall Time | t _f | | - | 23 | - | nS |
| Total Gate Charge | Q _g | V _{DS} =20V,I _D =20A, V _{GS} =10V | - | 90 | - | nC |
| Gate-Source Charge | Q _{gs} | | - | 14 | - | nC |
| Gate-Drain Charge | Q _{gd} | | - | 22 | - | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage ^(Note 3) | V _{SD} | V _{GS} =0V,I _S =20A | - | - | 1.2 | V |
| Diode Forward Current ^(Note 2) | I _S | | - | - | 90 | A |
| Reverse Recovery Time | t _{rr} | T _J =25°C, I _F =20A di/dt=100A/μs ^(Note 3) | - | 42 | - | nS |
| Reverse Recovery Charge | Q _{rr} | | - | 45 | - | nC |
| Forward Turn-On Time | t _{on} | Intrinsic turn-on time is negligible(turn-on is dominated by LS+LD) | | | | |

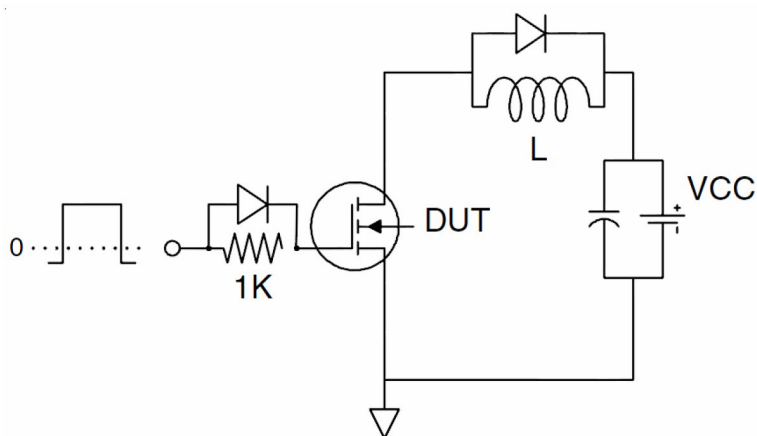
Notes:

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Surface Mounted on FR4 Board, t≤10sec.
- ③ Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%.
- ④ Guaranteed by design, not subject to production

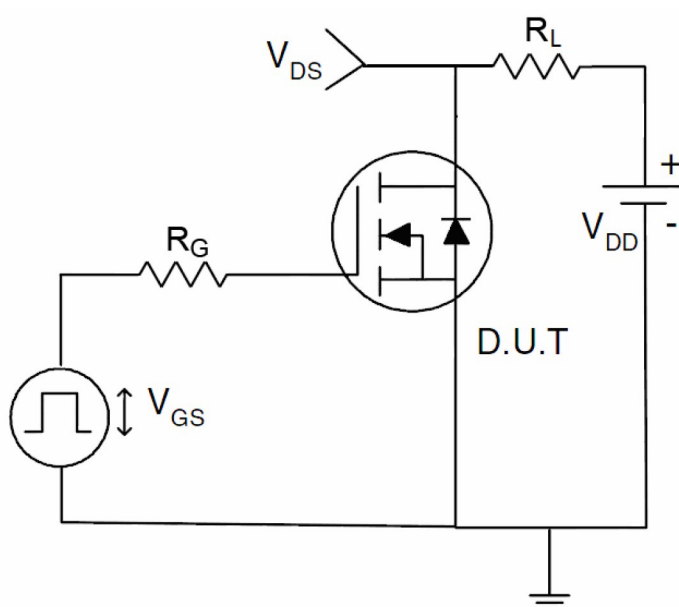
Test circuit



EAS test Circuit

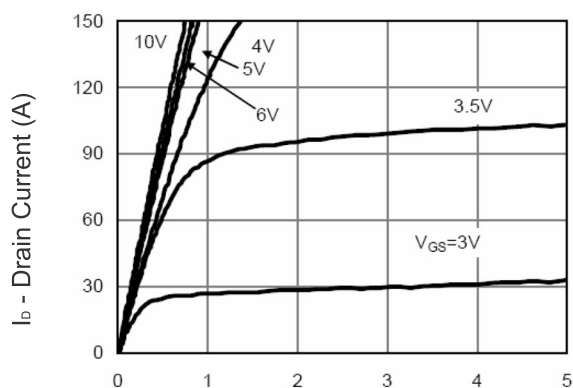


Gate charge test Circuit



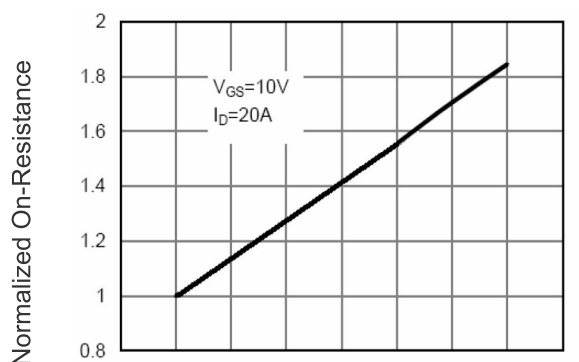
Switch Time Test Circuit

Typical Electrical and Thermal Characteristics (Curves)



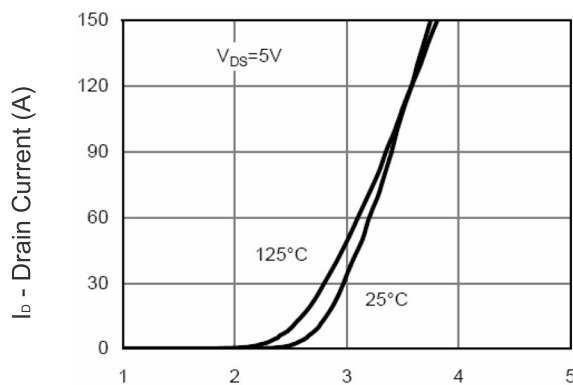
V_{DS} Drain-Source Voltage (V)

Figure 1 Output Characteristics



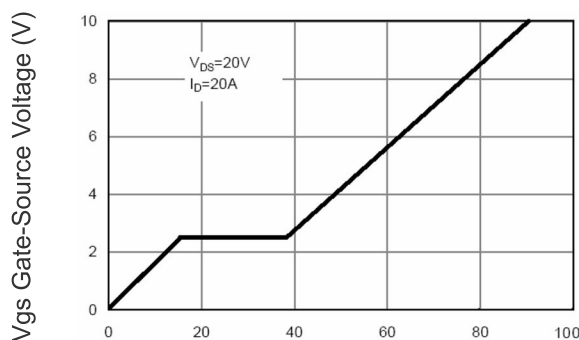
T_J -Junction Temperature(°C)

Figure 4 R_{dson} -Junction Temperature



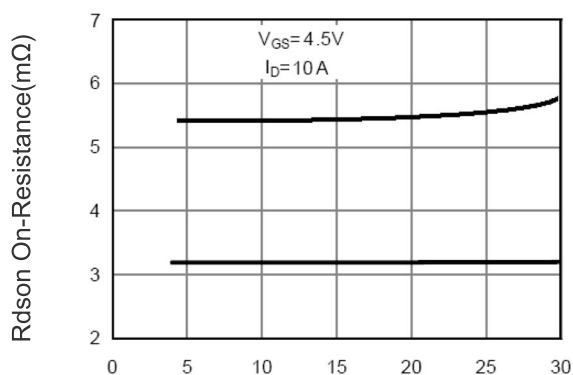
V_{GS} Gate-Source Voltage (V)

Figure 2 Transfer Characteristics



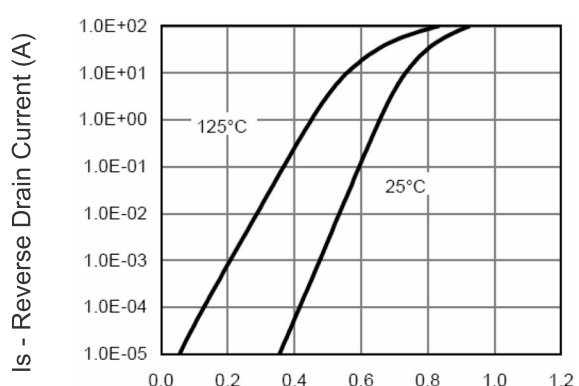
Q_g Gate Charge (nC)

Figure 5 Gate Charge



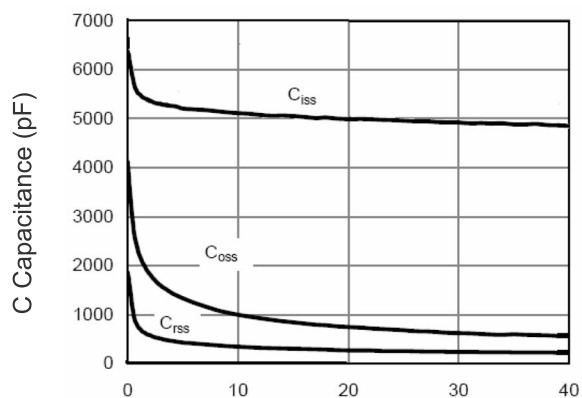
I_D - Drain Current (A)

Figure 3 R_{dson} - Drain Current

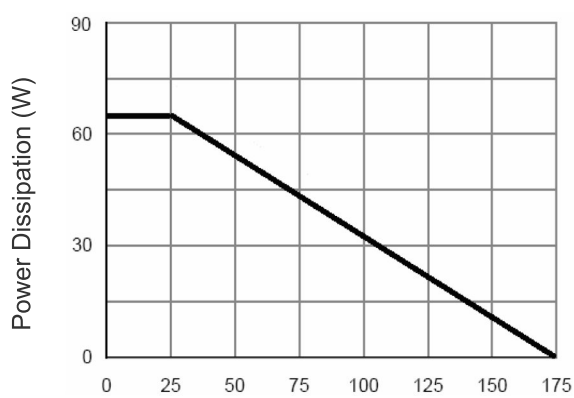


V_{SD} Source-Drain Voltage (V)

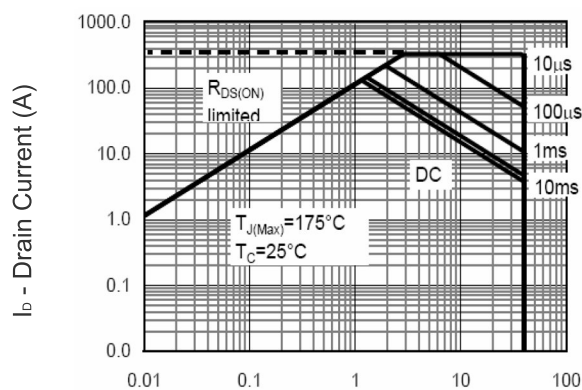
Figure 6 Source- Drain Diode Forward



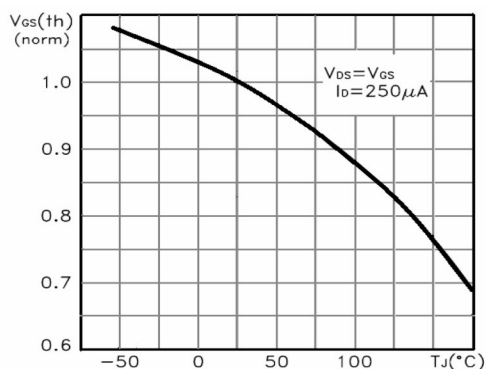
Vds Drain-Source Voltage (V)
Figure 7 Capacitance vs Vds



TJ -Junction Temperature(°C)
Figure 9 Power De-rating



Vds Drain-Source Voltage (V)
Figure 8 Safe Operation Area



TJ -Junction Temperature(°C)
Figure 10 VGS(th) vs Junction Temperature

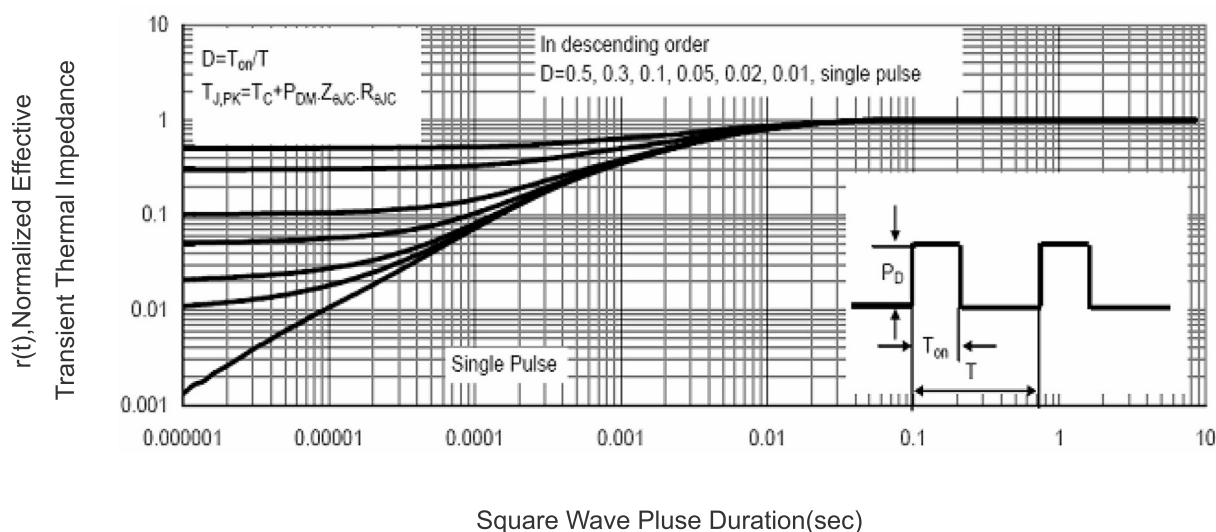
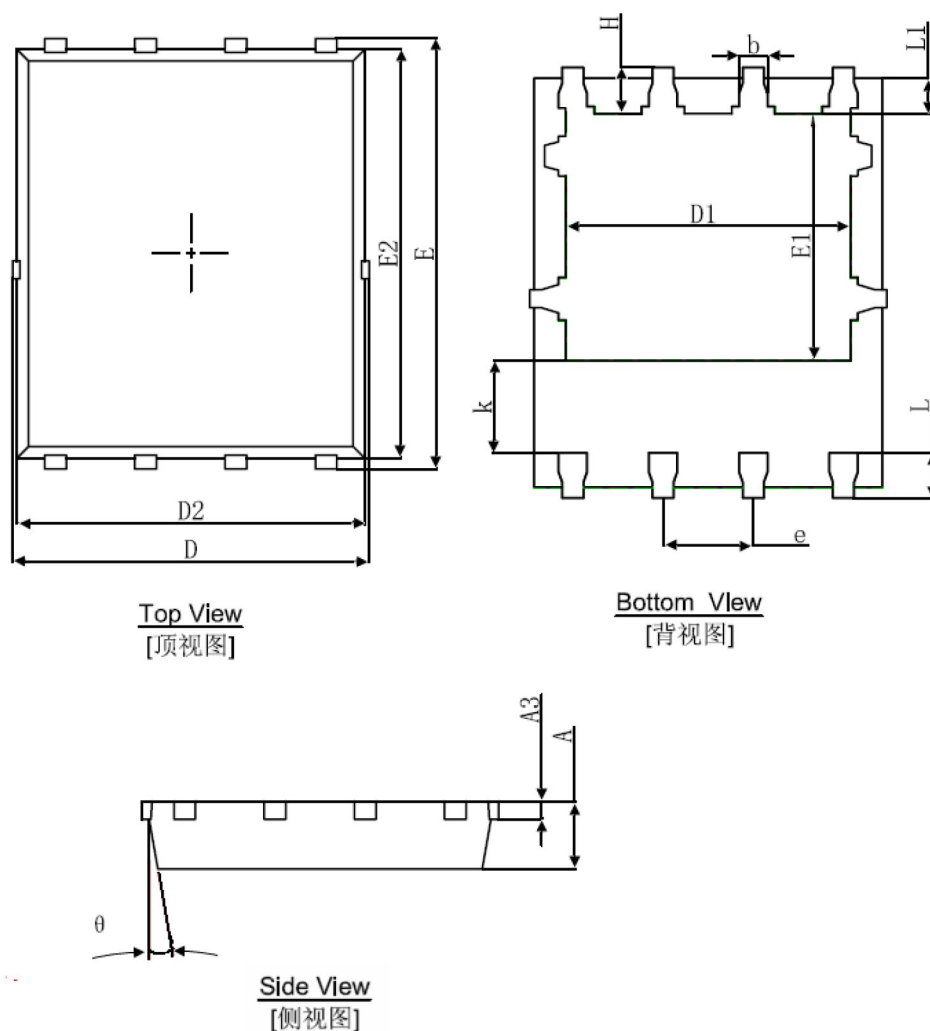


Figure 11 Normalized Maximum Transient Thermal Impedance

DFN5X6-8L Package Information



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|----------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 0.900 | 1.000 | 0.035 | 0.039 |
| A3 | 0.254REF. | | 0.010REF. | |
| D | 4.944 | 5.096 | 0.195 | 0.201 |
| E | 5.974 | 6.126 | 0.235 | 0.241 |
| D1 | 3.910 | 4.110 | 0.154 | 0.162 |
| E1 | 3.375 | 3.575 | 0.133 | 0.141 |
| D2 | 4.824 | 4.976 | 0.190 | 0.196 |
| E2 | 5.674 | 5.826 | 0.223 | 0.229 |
| k | 1.190 | 1.390 | 0.047 | 0.055 |
| b | 0.350 | 0.450 | 0.014 | 0.018 |
| e | 1.270TYP. | | 0.050TYP. | |
| L | 0.559 | 0.711 | 0.022 | 0.028 |
| L1 | 0.424 | 0.576 | 0.017 | 0.023 |
| H | 0.574 | 0.726 | 0.023 | 0.029 |
| θ | 8° | 12° | 8° | 12° |

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